

SEMICONDUCTOR STRUCTURE AND PREPARING METHOD THEREFOR

ABSTRACT

The present disclosure provides a semiconductor structure and a preparation method therefor. The semiconductor structure comprises a substrate, a chip and a first adhesive layer; the surface of the substrate is provided with an insulating layer; the chip is provided on the surface of the insulating layer by means of the first adhesive layer; the insulating layer is provided with a hole slot, the position of the hole slot corresponds to at least a part of the edge of the first adhesive layer, a second adhesive layer is provided in the hole slot, and at least a part of the surface of the second adhesive layer is connected to the first adhesive layer; and the elastic modulus of the second adhesive layer is less than the elastic modulus of the first adhesive layer.

[Fig. 11]